ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1	IPC Web Site for Information on IPC-1752 Standard					Form Type * Declaration Class *				erials and M	ials and Mfg Information						
Supplier Information																	
Company	Company name*				Company unique ID			Unique ID Authority					Respon	Response Date*			
onsemi													2024-04	2024-04-19			
Contact Name				Title - Contact				Phone - Contact*					Email -	Email - Contact*			
Product-Env-Stewards				Product Enviro Compliance				NA					Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative*				Title - Representative				Phone - Representative*				Email -	Email - Representative*				
Product-I	Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
	Requester	er Item Number Mfr Item N		Number	Number Mfr Item Name			Effective Da	ate \	Version	N	Manufacturing Site		Weigh	t*	UOM	Unit Type
	AR0522S A0-DP		SRSC09SUR	SC09SUR 5MP 1/2 CIS SO			2024-04-19	,		Т	TA1		291.23	l	mg	Each	
Manufacturing Proccess Information																	
	Terminal Pl	erminal Plating / Grid Array Material To		Cerminal Base Alloy J-STD		J-STD-020 MS	L Rating Peak F		rocess Body Temperature Max Time at Peak		ak Tempera	Temperature Number of		f Reflow Cycle	S		
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 4		4		260			С	30	seco	nds	3			
Comments						·											
For more	information	regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	62.83	mg		Misc.	proprietary data		0.2388	mg
			Supplier	Silicon (Si)	7440-21-3		61.9692	mg
			Supplier	Aluminum (Al)	7429-90-5		0.622	mg
Die Attach	2.76	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.035	mg
			Supplier	Ethylene Glycol	107-21-1		0.0276	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0828	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.5796	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.035	mg
Imaging Lens	66.68	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.334	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.334	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.334	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.334	mg m
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3334	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.334	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.334	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.3426	mg
Lid Attach	2.87	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9069	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1492	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.9069	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9069	mg
Mold Compound-Black	59.52	mg		Phenolic Resin	proprietary data		8.928	mg m
			Supplier	Oxirane	39817-09-9		8.928	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.7856	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.0928	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1904	mg
Substrate and Solder Mask	96.33	mg	Supplier	Acetophenone	98-86-2		1.8881	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		21.3756	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.2619	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.2716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3179	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3179	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.7761	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	9.633	mg
			Supplier	Copper (Cu)	7440-50-8	46.7201	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.7679	mg
Wire Bond - Au	0.24	mg	Supplier	Gold (Au)	7440-57-5	0.24	mg